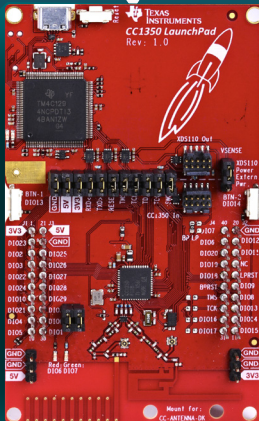




CC1350 LaunchPad™

// wireless microcontroller development kit for rapid prototyping.
LAUNCHXL-CC1350



LAUNCH
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START @
dev.ti.com/launchxl-cc1350

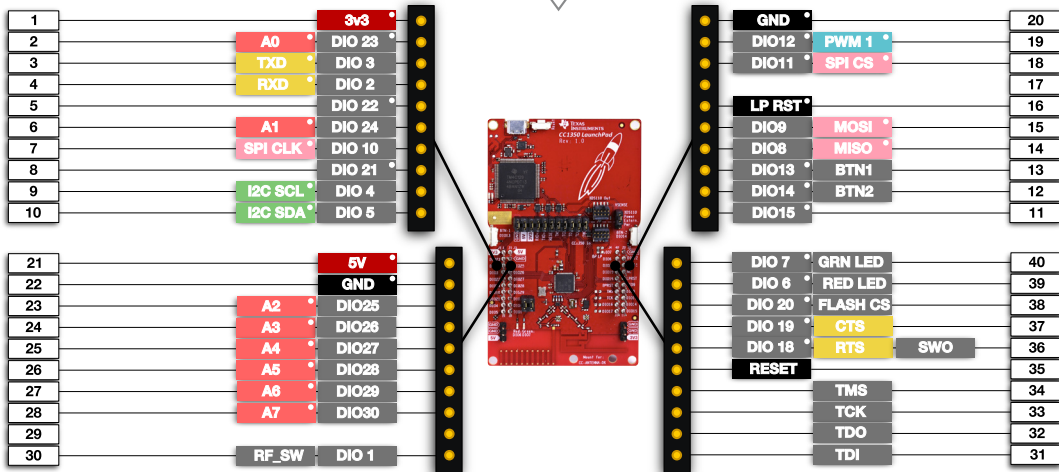


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○ Pin aligns with BoosterPack pinout standard.
Make your own BoosterPack @ www.ti.com/byob



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